

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP BLACK,UL94 V-0
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 3.0 AMP,AC/DC
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V,AC/Minute
- 2.3 CONTACT RESISTANCE: 100mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000 mΩ Min
- 2.5 Operation Temperature:-40°C to +125°C

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

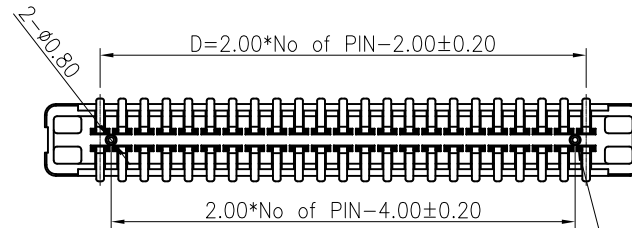
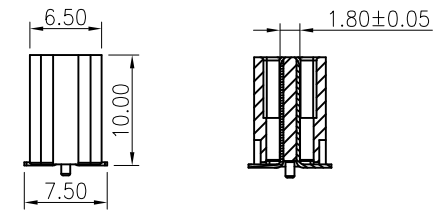
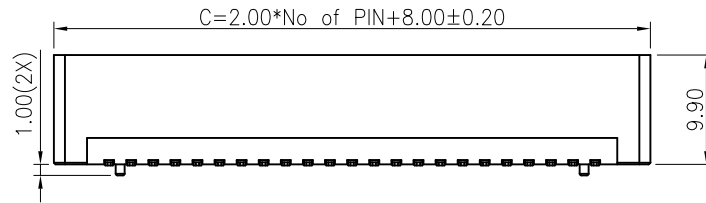
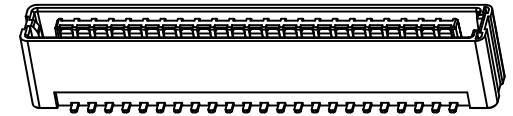
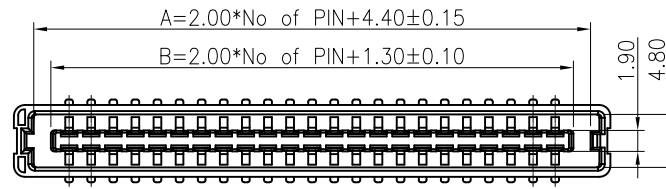
66G5-M XXX S1 100 R 01

Pin数码
SEE TABLE
006=2*03PIN
~
100=2*50PIN
(偶数PIN 任意选择)

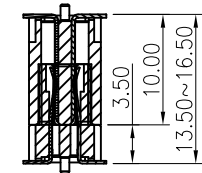
端子电镀:
S1=1u"Gold/Tin
S2=3u"Gold/Tin

高度:
100=10.00mm

包装方式:
R=REEL

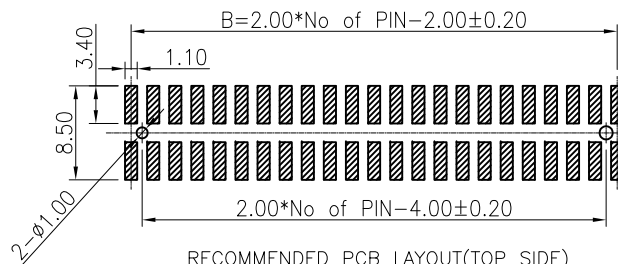


定位柱可以根据客户需求移动



MATING HEIGHT

组合高度可以从13.50~36.00mm



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05

					OPERATION		DRAW		Mr.Zeng		2024.04.20		SOLEPiN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.					
					X.X	±0.40	DESIGN		Jensen		2024.04.20							
					X.XX	±0.25	CHECK		Jack		2024.04.20							
					X.XXX	±0.15	APPROVE		Andy		2024.04.20							
AO		NEW		——	——	Angle	±3°					SHEET		1/1	TITLE:		66G5 2.00mm BTB 公头直立式 SMT H10.00mm	
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.		SP-1114	

客户图

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3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

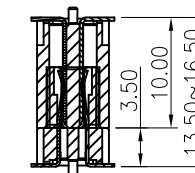
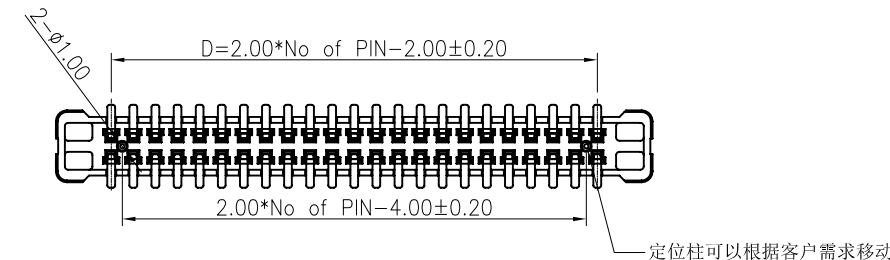
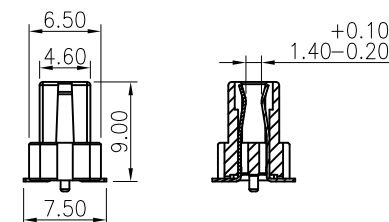
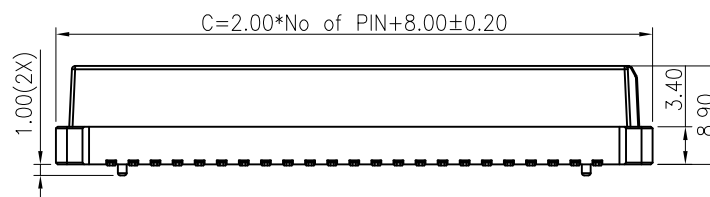
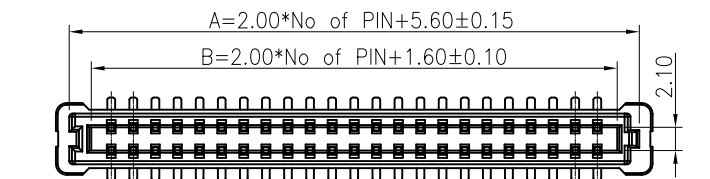
66G5-F XXX S1 090 R 01

Pin数码
SEE TABLE
010=2*05PIN
~
100=2*50PIN
(偶数PIN 任意选择)

端子电镀:
SN=Gold TIN
S1=1u"Gold/Tin
S2=3u"Gold/Tin

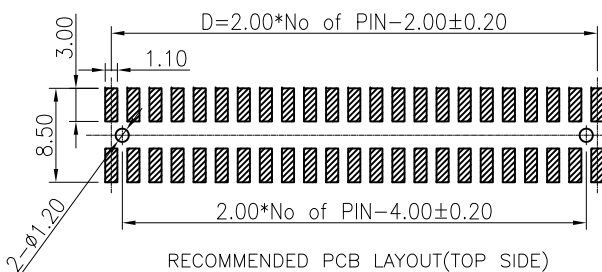
高度:
090=9.00mm

包装方式:
R=REEL



MATING HEIGHT

组合高度可以从13.50~36.00mm



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PCB BOARD TOLERANCE±0.05

					OPERATION		DRAW		Mr.Zeng		2024.04.20		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
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					X.XX	±0.25	CHECK		Jack		2024.04.20					
					X.XXX	±0.15	APPROVE		Andy		2024.04.20					
A0		NEW			Angle	±3'					2024.04.20		SHEET	1/1	TITLE:	66G5 2.00mm BTB 母座直立式 SMT 9.00mm
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1115	